

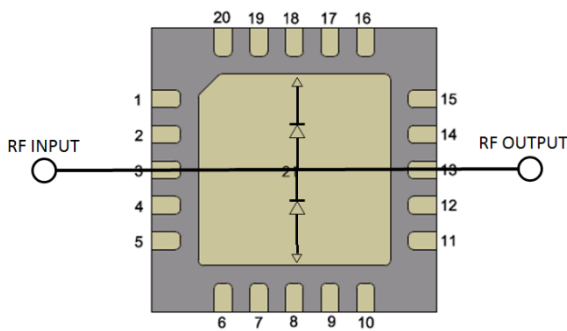
Product Overview

Qorvo's QPP2209 is a high power VPIN limiter robust to short-pulse input signals up to 40W. It offers exceptionally low insertion loss over a wide bandwidth and requires no DC bias. The QPP2209 is housed in a low-cost plastic over-molded QFN package.

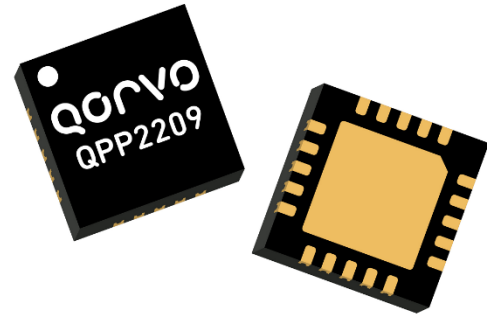
The QPP2209 is internally matched to 50 ohms and operates from 8 to 12 GHz with typical insertion loss less than 0.5dB and flat leakage below 19dBm. It is capable of withstanding 40W of incident power under short-pulse conditions. It is well suited for both commercial and defense related applications.

Lead-free and RoHS compliant.

Functional Block Diagram



Top View



20L 4 x 4 mm OVM QFN Package

Key Features

- Frequency Range: 8 to 12 GHz
- Insertion Loss: < 0.5 dB
- Peak Power Handling: 40 W (pulsed)
- Flat Leakage: < 19 dBm
- Spike Leakage < 20.5 dBm
- Passive (no DC bias required)
- Recovery time < 30 ns
- Package Dimensions: 4.00 x 4.00 x 0.85 mm

Performance is typical across frequency. Please reference electrical specification table and data plots for more details.

Applications

- Receive Chain Protection
- Commercial and Military Radar

Ordering Information

Part	Description
QPP2209TR7	8–12 GHz 40W VPIN Limiter, 500 pcs, 7-inch reel
QPP2209TR7X	8–12 GHz 40W VPIN Limiter, 50 pcs, 7-inch reel
QPP2209EVB01	Evaluation Board

Absolute Maximum Ratings

Parameter	Rating
Incident Power, Pulsed ¹ , 50 Ω, 25 °C	46 dBm
Incident Power, Pulsed ¹ , 50 Ω, 85 °C	46 dBm
Incident Power, CW, 50 Ω, 25 °C	37 dBm
Incident Power, CW, 50 Ω, 85 °C	34 dBm
Mounting Temperature (30 s max)	260 °C
Storage Temperature	-40 to 150 °C

Note:

¹ Pulse conditions: PW = 100 us, Duty Cycle = 10%

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability.

Recommended Operating Conditions

Parameter	Min	Typ.	Max	Units
Passive – No Bias				
Temperature Range	-40	+25	+85	°C

Electrical specifications are measured at specified test conditions. Specifications are not guaranteed over all recommended operating conditions.

Electrical Specifications

Parameter	Conditions ⁽¹⁾	Min	Typ.	Max	Units
Operational Frequency Range		8.0		12.0	GHz
Insertion Loss	8 GHz		0.32	0.75	dB
	10 GHz		0.35	0.90	
	12 GHz		0.47	1.00	
Input Return Loss	8 GHz		25		dB
	10 GHz		21		
	12 GHz		15		
Output Return Loss	8 GHz		30		dB
	10 GHz		21		
	12 GHz		15		
Flat Leakage Power at P _{IN} > 30 dBm (Pulse)	8 GHz	14	18.2	19.5	dBm
	10 GHz	14	18.0	19.5	
	12 GHz	14	18.2	19.5	
Pulse Recovery Time			<30		ns
Spike Leakage			20.5		dBm
Insertion Loss Temperature Coefficient			0.004		dB/ °C

Notes:

1. Test conditions unless otherwise noted: Temp = +25 °C, 50 Ω system. S-Parameter CW, Power Pulse Parameter: PW = 100µs, Duty Cycle = 10%.

Thermal and Reliability Information

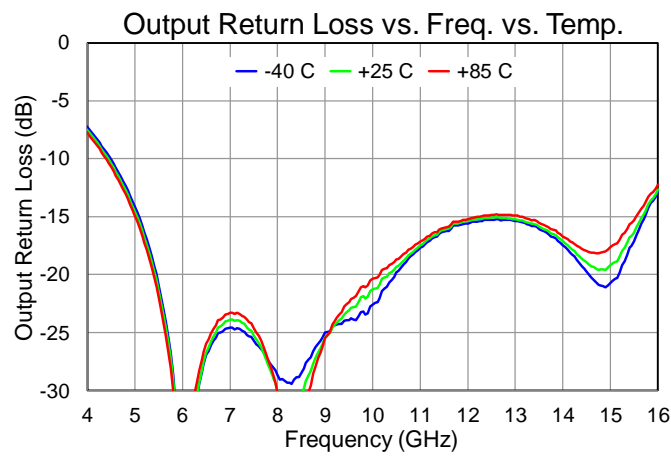
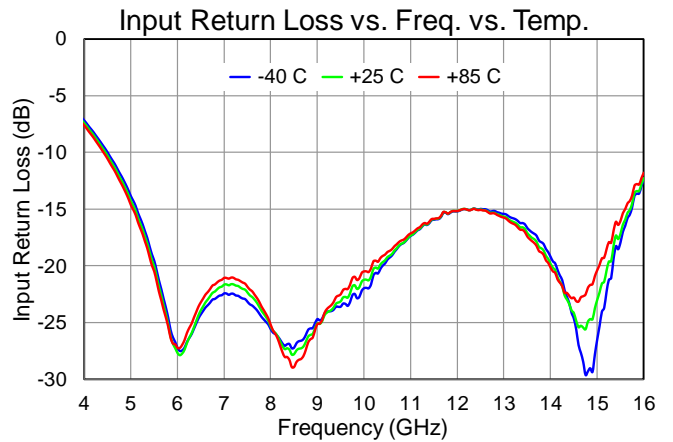
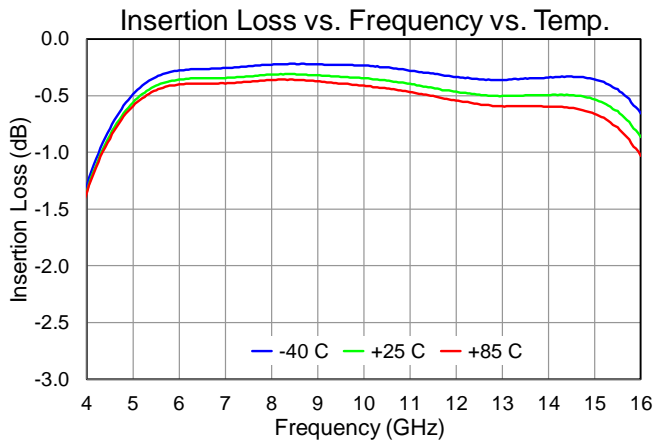
Parameter	Test Conditions	Value	Units
Incident Power (RF Operational Life Test ⁽¹⁾)	10 GHz Pulsed, PW=100 us, DC=10%, 50 Ω, 25 °C	40	W

Notes:

1. Test terminated after 100 hours.

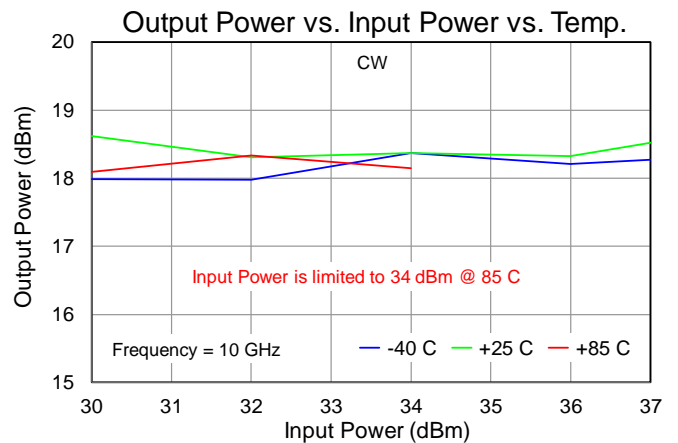
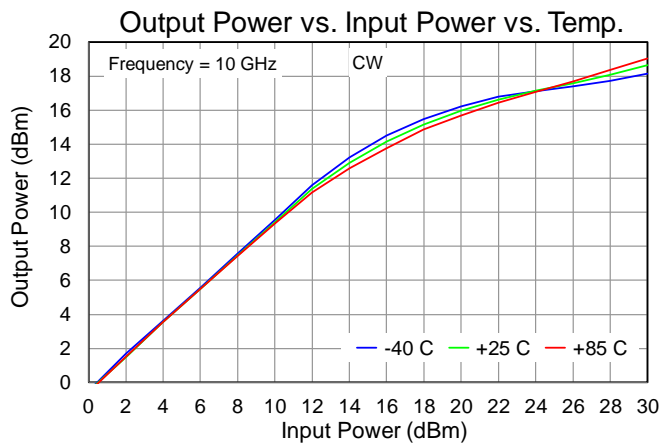
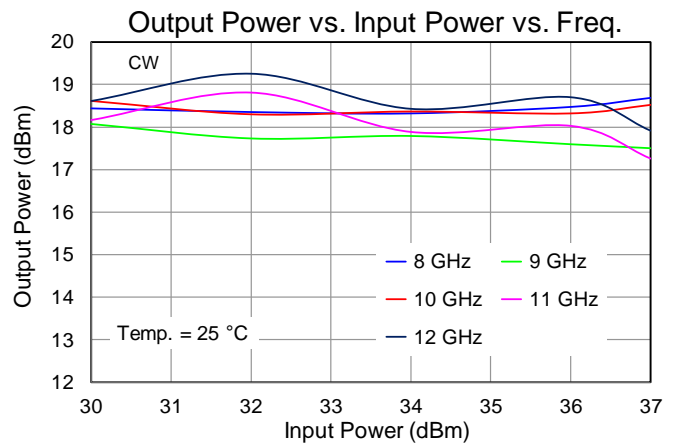
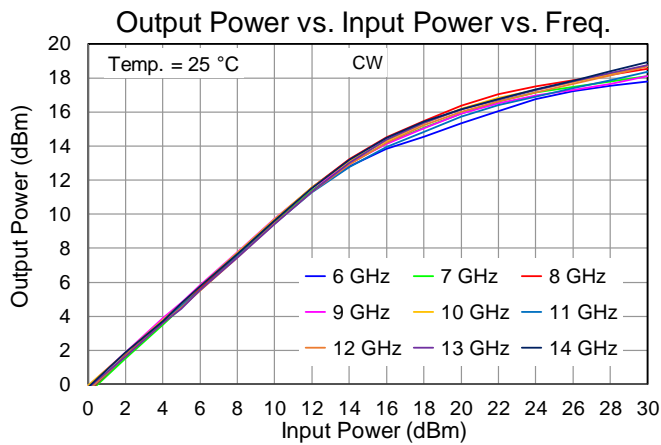
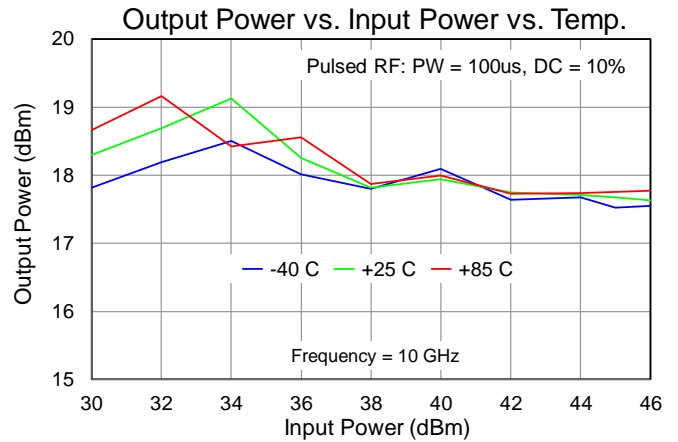
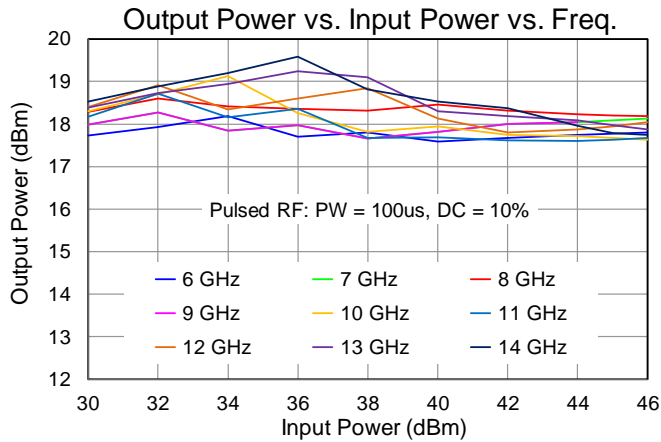
Performance Plots – Small Signal

Test conditions unless otherwise noted: Temp.=+25 °C, CW

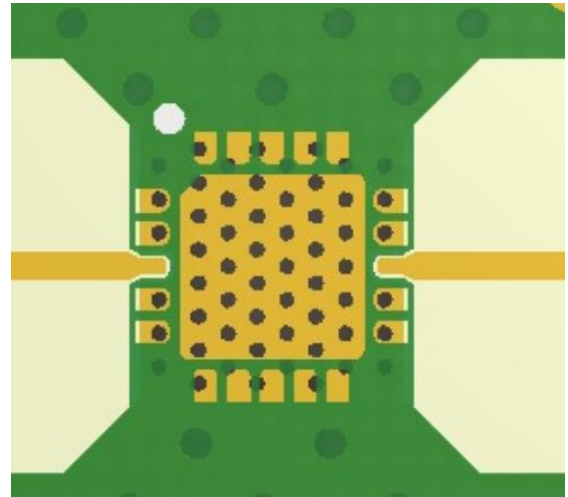
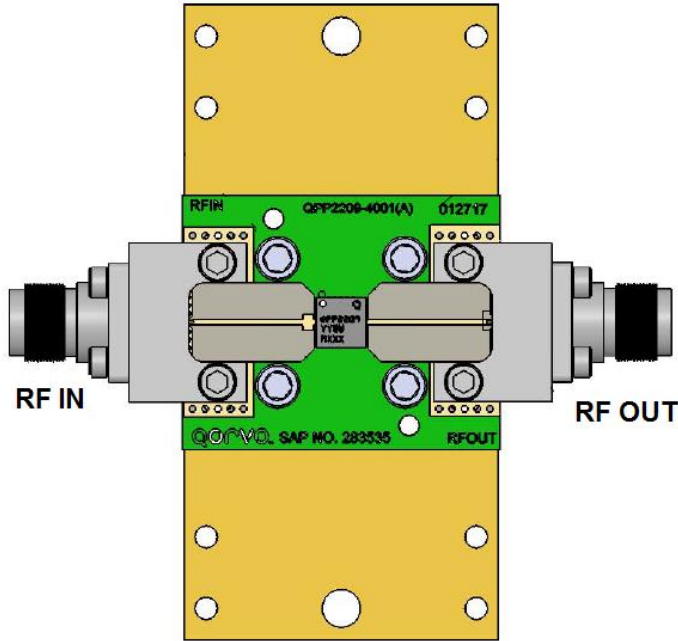


Performance Plots – Large Signal

Test conditions unless otherwise noted: Pulsed RF: PW = 100us, DC = 10%; Temp.=+25 °C



Application Circuit and Evaluation Board (EVB) and Mounting Detail




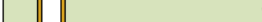



Notes:

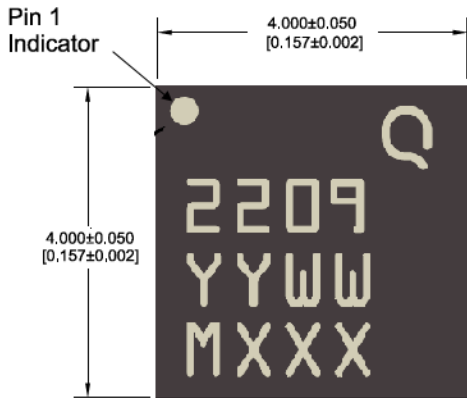
1. See Evaluation Board PCB Information for material and stack up.

Evaluation Board PCB Information

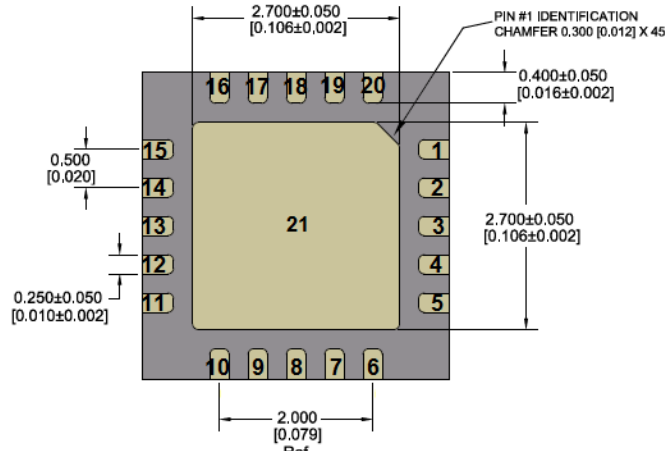
Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type
	SILKSCREEN_TOP			Legend
	Surface Material	0.4mil	Solder Resist	Solder Mask
	METAL1_TOP	0.7mil		Signal
	Core	8.0mil	ROGERS 4003C	Dielectric
	METAL2_BOT	0.7mil		Signal
Total thickness: 9.8mil				

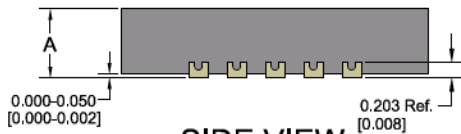
Package Marking, Pad Configuration and Description



TOP VIEW



BOTTOM VIEW



SIDE VIEW

A	MAX.	0.900 [0.035]
	NOM.	0.850 [0.033]
	MIN.	0.800 [0.031]

LASER MARK NOTES:

- 2209 IS PART #
- YY IS THE LAST TWO DIGITS OF THE CALENDAR YEAR
- WW IS THE WEEK NUMBER OF THE ASSEMBLY LOT START
- MXXX IS THE BATCH ID

NOTES: UNLESS OTHERWISE SPECIFIED;

1. TESTED QPP2209
2. PACKAGE IS MOLD ENCAPSULATED.
3. PACKAGE EXPOSED METALLIZATION ARE GOLD PLATED.

UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN mm [INCHES]

.XX = ± .25 [.001]
 TOLERANCES .XXX = ± .100 [.004] ANGLES = 0.5 °
 .XXXX = ± .0254 [.001]

Pad No.	Label	Description
1, 2, 4–12, 14–20	NC	No connection; may be grounded if desired
3	RF Input	RF Input, matched to 50 Ohms, not DC blocked
13	RF Output	RF Output, matched to 50 Ohms, not DC blocked
21 (Slug)	GND	On PCB, multiple copper-filled vias should be employed under the center pad to minimize inductance and thermal resistance

NOTE: The RF Input and RF Output ports are not interchangeable.

Assembly Notes

1. Compatible with lead-free soldering process with 260°C peak reflow temperature.
2. The use of no-clean solder to avoid washing after soldering is recommended.
3. Contact plating: Ni-Pd-Au

Recommended Soldering Profile

